

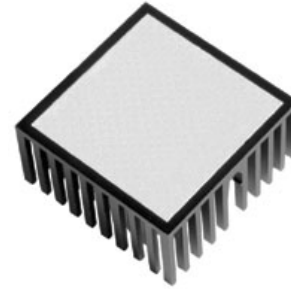


BOARD LEVEL COOLING - 3718

3718 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

| Part Number | Device Type |
|---------------|-------------|
| 371824B00032G | BGA, FPGA |
| 371824B00034G | BGA, FPGA |



HEAT SINK DETAILS

| Property | Details |
|----------------------------------------------|-------------------------------------------|
| Material | Aluminum |
| Finish | Black Anodize |
| Device Attachment Options | Tape |
| Thermal Interface Material: 371824B00032G | T405R Chomerics Tape for Metal surfaces |
| Thermal Interface Material: 371824B00034G | T410R Chomerics Tape for Plastic Surfaces |

| Property | Details |
|------------------------------|----------------------|
| Heat Sink Width (mm) | 35.00 |
| Heat Sink Length (mm) | 35.00 |
| Heat Sink Height (mm) | 7.00 |
| Heat Sink Mounting Direction | Horizontal, Vertical |

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

